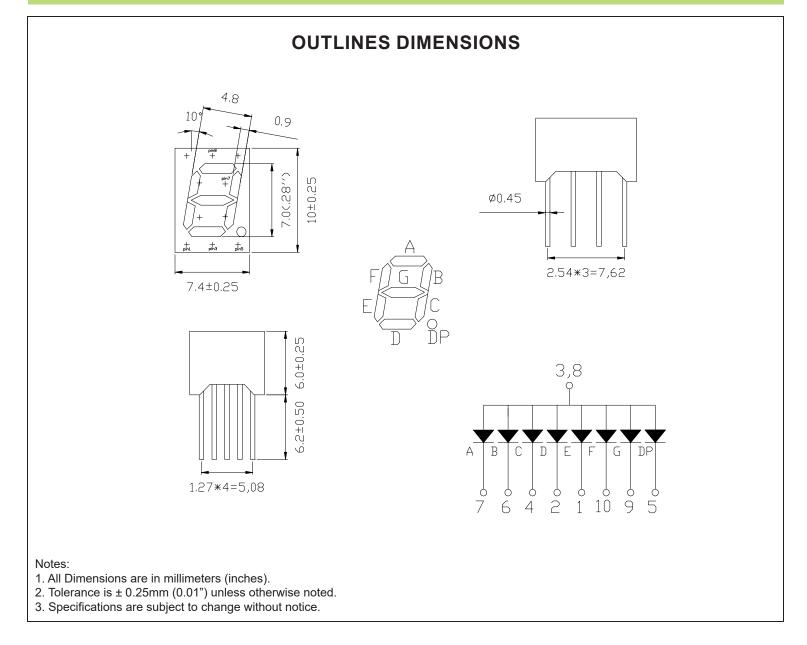


#### SPECIFICATIONS

# CDSAP28G2WBF



Part Number	Chip Material	Color of Emission	r of Emission Lens Type	
CDSAP28G2WBF	InGaAIP	Green	White Segment	Common Anode





#### ABSOLUTE MAXIMUM RATINGS

### (TA=25°C

Parameter	Symbol	Max Rating	Unit			
Power Dissipation	PD	80	mW			
Pulse Forward Current	lfp	120	mA			
Continuous Forward Current	lF	20	mA			
Reverse Voltage Segment	VR	5	V			
Operating Temperature Range	Topr	-25~+85	°C			
Storage Temperature Range	Тѕтс	-30~+85	°C			
IFP = Pulse Width $\leq$ 10 ms, Duty Ratio $\leq$ 1/10. Soldering Condition: 260 °C/ 5sec						

### **OPTICAL-ELECTRICAL CHARACTERISTICS**

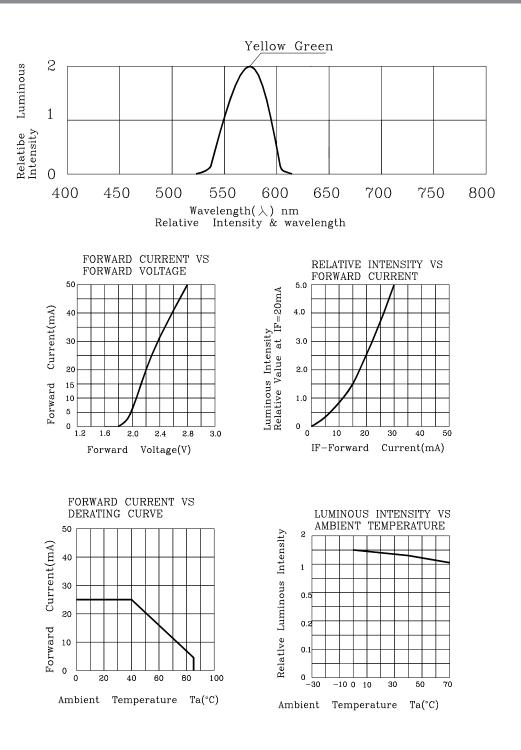
(TA=25°C)

Deremeter	Symbol	Test Condition	Value			Linit
Parameter			Min	Тур	Max	Unit
Luminous Intensity	١v	l⊧ = 10mA	10	20	-	mcd
Forward Voltage	Vf	l⊧ = 20mA	-	2.1	2.5	V
Reverse Leakage Current	lr	V <sub>R</sub> = 5V	-	-	20	μΑ
Dominant Wavelength	λD	l⊧ = 20mA	-	570	-	nm
Spectral Radiation Bandwidth	Δλ	l⊧ = 20mA	-	20	-	nm





## **OPTICAL CHARACTERISTIC CURVES**

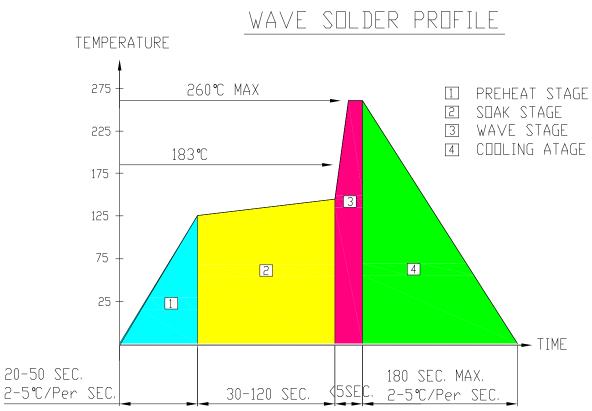






#### SOLDERING CONDITIONS – DISPLAY TYPE LED

## • RECOMMEND SOLDERING PROFILE



#### SOLDERING IRON

Basic spec is  $\leq$ 4 sec when 260°C. If temperature is higher, time should be shorter (+10°C→1 sec). Power dissipation of Iron should be smaller than 15W, and temperature should be controllable. Surface temperature of the device should be under 230°C.

### REWORK

Customer must finish rework within ≦4 sec under 245°C.

